L Number	Hits	Search Text	DB	Time stamp
1	121577	potting or encapsulat$3	USPAT; US-PGPUB	2003/03/14 14:29
2	159662	cure or curing	USPAT; US-PGPUB	2003/03/14 14:23
3	515407	wafer or substrate	USPAT; US-PGPUB	2003/03/14 14:23
4	217	(potting or encapsulat$3) with (cure or curing) with (wafer or substrate)	USPAT; US-PGPUB	2003/03/14 14:24
5	396348	semiconductor or "integrated circuit"	USPAT; US-PGPUB	2003/03/14 14:29
6	146	((potting or encapsulat$3) with (cure or curing) with (wafer or substrate)) and (semiconductor or "integrated circuit")	USPAT; US-PGPUB	2003/03/14 14:30
-	1114	thermoset with thermosetting	USPAT; US-PGPUB	2003/03/14 14:01
-	251	(thermoset with thermosetting) with (cure or curing)	USPAT; US-PGPUB	2003/03/14 14:08
-	110338	encapsulat$3	USPAT; US-PGPUB	2003/03/14 14:09
-	2044323	surface or wafer	USPAT; US-PGPUB	2003/03/14 14:10
-	39	((thermoset with thermosetting) with (cure or curing)) with (surface or wafer)	USPAT; US-PGPUB	2003/03/14 14:10
-	16	encapsulat$3 and (((thermoset with thermosetting) with (cure or curing)) with (surface or wafer))	USPAT; US-PGPUB	2003/03/14 14:19
-	3317	(cure or curing) with (potting or encapsulat$3)	USPAT; US-PGPUB	2003/03/14 14:20

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L Number	Hits	Search Text	DB	Time stamp
1	1114	thermoset with thermosetting	USPAT; US-PGPUB	2003/03/14 14:01
2	159662	cure or curing	USPAT; US-PGPUB	2003/03/14 14:01
3	251	(thermoset with thermosetting) with (cure or curing)	USPAT; US-PGPUB	2003/03/14 14:08
4	110338	encapsulat$3	USPAT; US-PGPUB	2003/03/14 14:09
5	2044323	surface or wafer	USPAT; US-PGPUB	2003/03/14 14:10
6	39	((thermoset with thermosetting) with (cure or curing)) with (surface or wafer)	USPAT; US-PGPUB	2003/03/14 14:10
7	16	encapsulat$3 and (((thermoset with thermosetting) with (cure or curing)) with (surface or wafer))	USPAT; US-PGPUB	2003/03/14 14:10

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